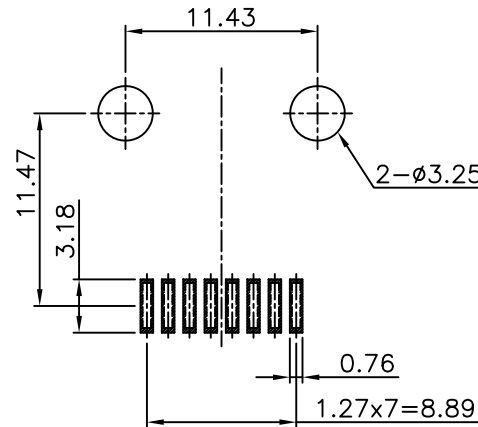
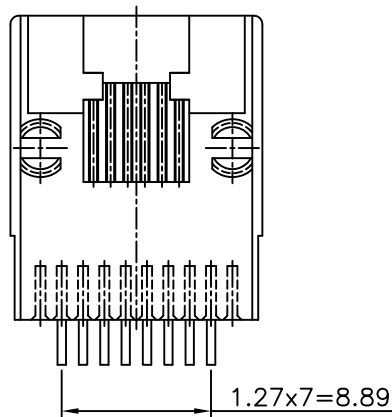
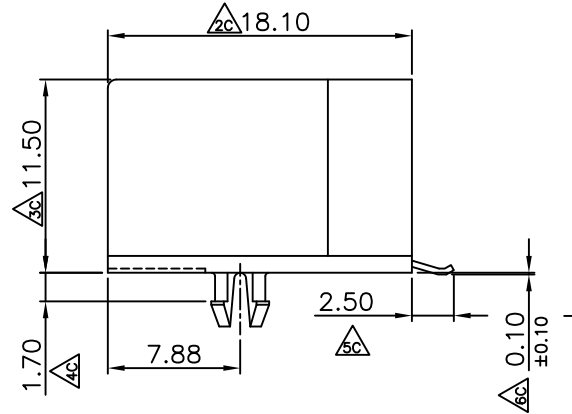
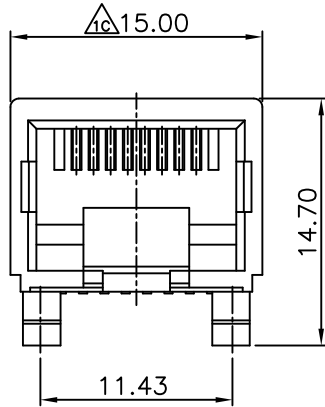


RoHS compliant



PCB LAYOUT/TOP VIEW

NOTES

MATERIAL

1. HOUSING MATERIAL : HIGH TEMP THERMOPLASTIC
FLAMMABILITY RATING UL94V-0.
2. CONTACT MATERIAL : PHOSPHOR BRONZE
3. PLATING : GOLD LATING OVER NICKEL IN CONTACT
TIN PLATING OVER NICKEL IN SOLDER AREA.
: FU", 3U", 6U", 15U", 30U", 50U".

ELECTRICAL

1. VOLTAGE RATING : 125 VAC RMS.
2. CURRENT RATING : 1.5 AMP.
3. CONTACT RESISTANCE : 40 MILLIOHMS MAX.
4. INSULATION RESISTANCE : 1000 MEGOHMS MIN @ 500V DC .
5. DIELECTRIC STRENGTH : 1000V VAC RMS 60Hz. 1MIN.

MECHANICAL

1. DURRABILITY : 750 CYCLES MIN.
2. PCB RETENTIONPRE-SOLDER : 1 LB MIN.

ENVIRONMENTAL:

1. STORAGE : -40°C~+85°C.
2. OPERATION : -40°C~+85°C.
3. IR Reflow Soldering Temperature:255°C TO 265°C.

Mates With Modular Plug Conforming TO FCC Part 68. Subpart F.

P/N:RJ56S-8811-001551X

56S RJ45 90° SMT SERIES PCB JACK

POSITIONS (金針位置):

8-POSITIONS (8P)

CONTACTS (金針根數):

8-8CONTACTS (8C)

PORTS (窗口):

11-1X1

SHIELD (屏蔽壳):

0-Without SHIELD (无屏蔽壳)

IRON PEG (铁脚定位脚):

0-Without Iron PEG (无铁脚)

HOUSING PEG (塑胶定位柱):

1-Mushroom feet (香菇脚)

PACKING TYPE (包装):

1-REEL (卷带包装)

2-PVC TRAY (盘装)

COLOR (颜色):

1-BLACK (黑色)

7-BLUE (蓝色)

PLASTIC (塑料):

4-LCP; 5-PA9T

GOLD PLATING (镀金厚度):

1-1U"; 5-6U"; 6-15U"

7-30U"; 8-50U";

GENERAL TOLERANCE

.X ±0.35 X.° ±2°

.XX ±0.25 .X° ±1°

.XXX ±0.15 .XX° ±0.5°

PROJECT



DRAWN

Gene Li

2019/06/13

CHECKE

JH

APPROVE

UNIT mm

SCALE 1:1

SHEET 1/1

X-SHUN 东莞市祥舜电子科技有限公司
DONGGUAN X-SHUN ELECTRONIC TECHNOLOGY CO., LTD

PART NO. RJ56S-8811-010551X

TITLE: RJ45 8P8C 90° SMT L=18.1MM PCB JACK

REV A0 DRAWING NO. RJ56S-88

REV ECN NO

DESCRIPTION

DATE

SIGNATURE